

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/07/2022

Details for "TAS5352ADDVR"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TAS5352ADDVR	NIPDAU	Level-3-260C-168 HR	TI TAIWAN A/T	DDV   44	14x6.1x1.2	270.1

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Aluminum and Its Alloys	Aluminum	7429-90-5	0.000004	0.000166	2	0.000001	0
Copper and Its Alloys	Copper	7440-50-8	2.412399	99.997223	999972	0.893207	8932
Copper and Its Alloys	Iron	7439-89-6	0.000011	0.000456	5	0.000004	0
Other Inorganic Materials	Sulfur	7704-34-9	0.000002	0.000083	1	0.000001	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000008	0.000332	3	0.000003	0
Precious Metals	Silver	7440-22-4	0.000042	0.001741	17	0.000016	0
Sub-Total			2.412466	100	1000000	0.893232	8932
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	2.632674	84.500014	845000	0.974765	9748
Thermoplastics	Epoxy	85954-11-6	0.482916	15.499986	155000	0.178803	1788
Sub-Total			3.11559	100	1000000	1.153568	11536
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	83.09073	97.41	974100	30.764907	307649
Copper and Its Alloys	Iron	7439-89-6	2.0472	2.4	24000	0.75799	7580
Copper and Its Alloys	Phosphorus	7723-14-0	0.02559	0.03	300	0.009475	95
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.02559	0.03	300	0.009475	95
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.02559	0.03	300	0.009475	95
Zinc and Its Alloys	Zinc	7440-66-6	0.0853	0.1	1000	0.031583	316
Sub-Total			85.3	100	1000000	31.582904	315829
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	1.460472	95.120031	951200	0.54075	5407
Precious Metals	Gold	7440-57-5	0.011976	0.779993	7800	0.004434	44
Precious Metals	Palladium	7440-05-3	0.062951	4.099977	41000	0.023308	233
Sub-Total			1.535399	100	1000000	0.568492	5685
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	139.628513	84.999999	850000	51.698404	516984
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	1.971226	1.2	12000	0.72986	7299
Other Plastics and Rubber	Carbon Black	1333-86-4	0.492807	0.3	3000	0.182465	1825
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.492807	0.3	3000	0.182465	1825
Other Plastics and Rubber	Silicone	218163-11-2	4.928065	3	30000	1.82465	18246
Thermoplastics	Epoxy	85954-11-6	16.755422	10.2	102000	6.203809	62038
Sub-Total			164.26884	100	1000000	60.821653	608217
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	13.450534	100	1000000	4.980151	49802
Sub-Total			13.450534	100	1000000	4.980151	49802
<b>Total</b>			270.082829			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.